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a top-half mold and a bottom-half mold for forming a cavity as a

a plunger for forcing the resin out of the transfer pot into said cavity;

pressure adjusting means for reducing the pressure in said cavity when

2. A transfer molding apparatus according to Claim 1, wherein said top-half mold and said bottom-half mold form a plurality of cavities interconnected, and wherein said pressure adjusting means reduces the pressure of the cavities every time a specified amount of resin is supplied into any one of a plurality of cavities.

3. A transfer molding apparatus according to Claim 1, wherein said pressure adjusting means includes position detecting means for detecting the position of said plunger when a specified amount of resin has been supplied into said cavity.

20 4. A transfer molding apparatus according to Claim 2, wherein said pressure adjusting means includes position detecting means for detecting the position of said plunger when a specified amount of resin has been supplied into said cavity.

5. A transfer molding apparatus according to Claim 1, wherein said  
25 pressure adjusting means includes time counting means for counting time  
from the start of movement of said plunger until a specified amount of said  
resin has been supplied into said cavity.

6. A transfer molding apparatus according to Claim 2, wherein said pressure adjusting means includes time counting means for counting time from the start of movement of said plunger until a specified amount of said resin has been supplied into said cavity.

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A method for manufacturing semiconductor devices comprising the steps of:

placing a semiconductor-element-mounted lead frame between a top-half mold and a bottom-half mold; and

reducing the pressure in a cavity formed by said top-half mold and said

10 bottom-half mold when a specified amount of resin has been supplied into said cavity.

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